

4. (AMENDED) The front-and-back electrically conductive substrate as claimed in claim 1, further comprising a pad for mounting a semiconductor component formed on at least the first surface of the front-and-back electrically conductive substrate.

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5. (AMENDED) The front-and-back electrically conductive substrate as claimed in claim 1, further comprising a thin film composed of a wiring pattern layer and an insulation layer formed on at least the first surface of the front-and-back electrically conductive substrate.

6. (AMENDED) The front-and-back electrically conductive substrate as claimed in claim 1, wherein the insulation material of the insulative substrate includes a material that absorbs a difference in a coefficient of thermal expansion between the insulation material and a mounted semiconductor component.